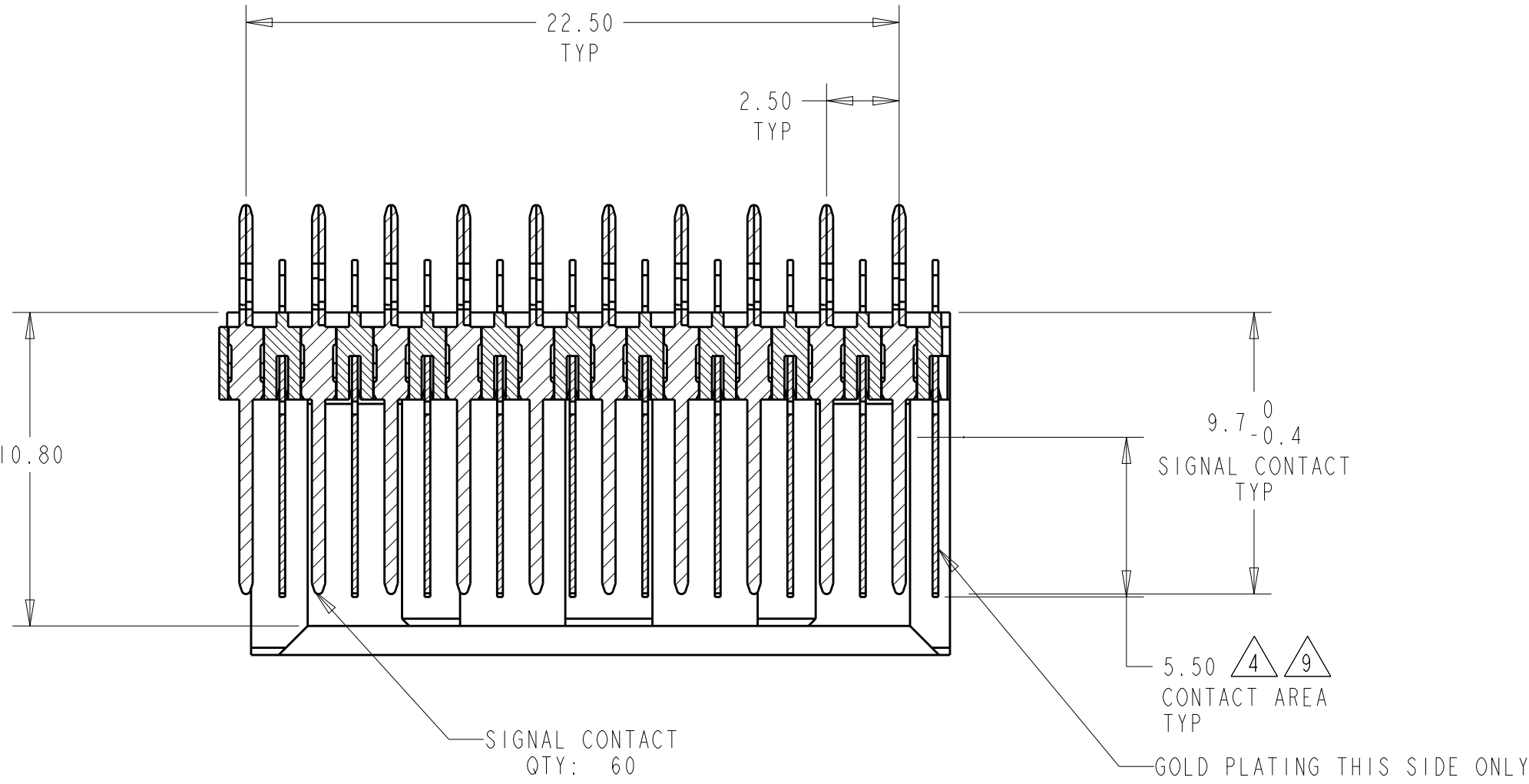
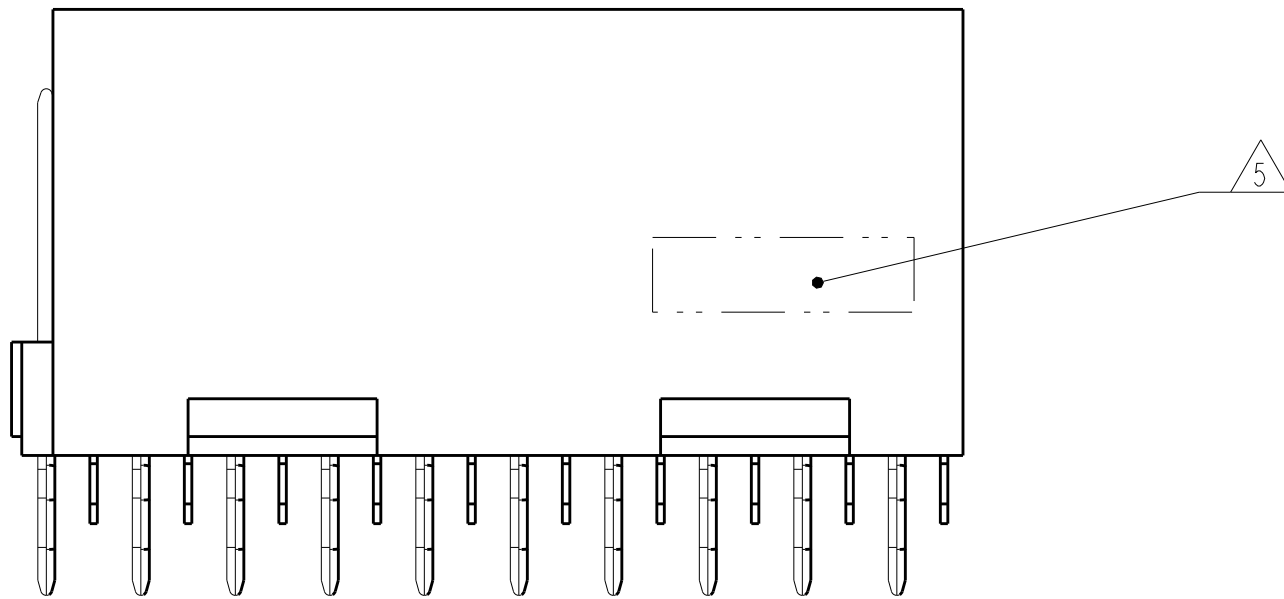
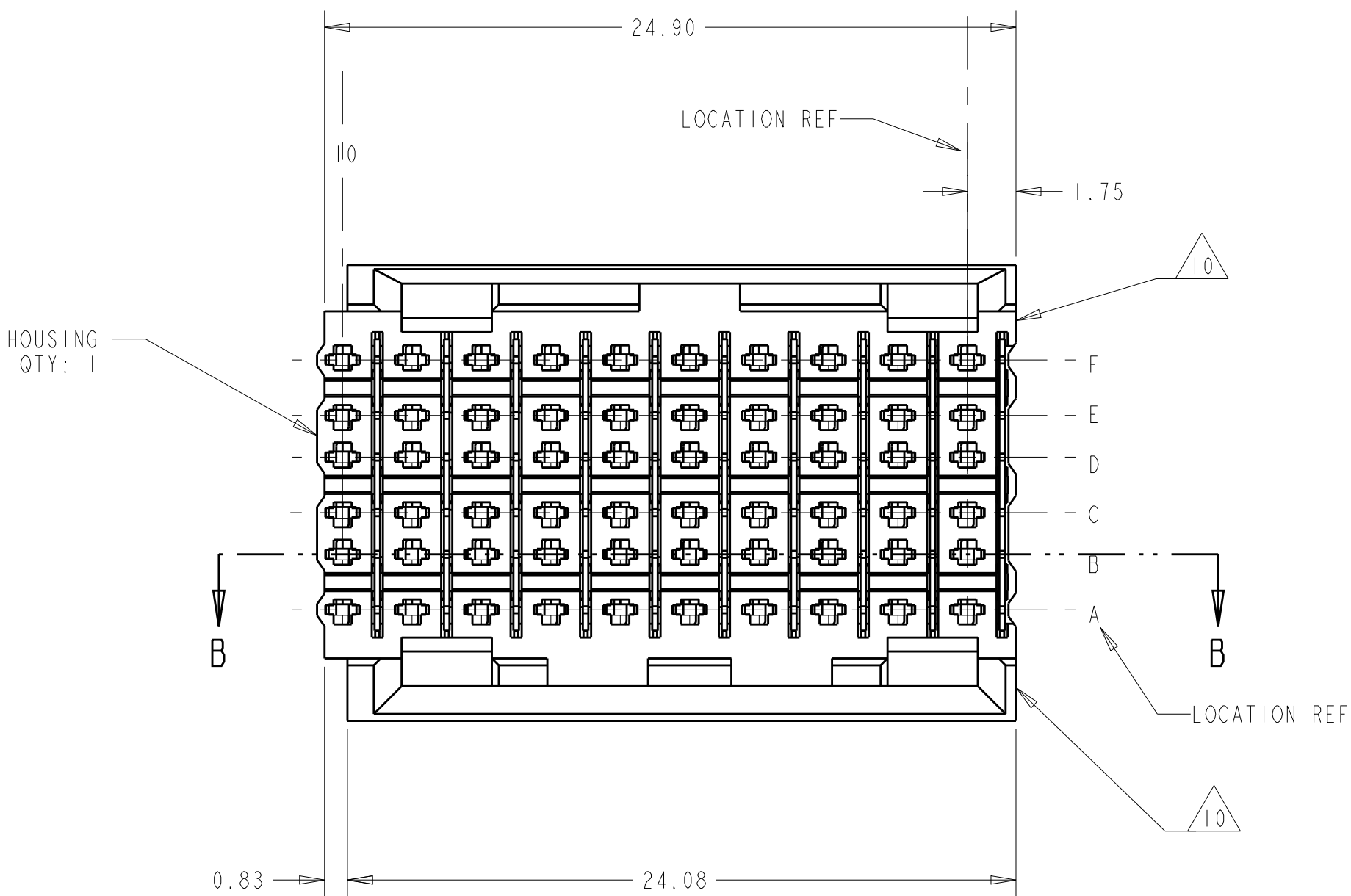


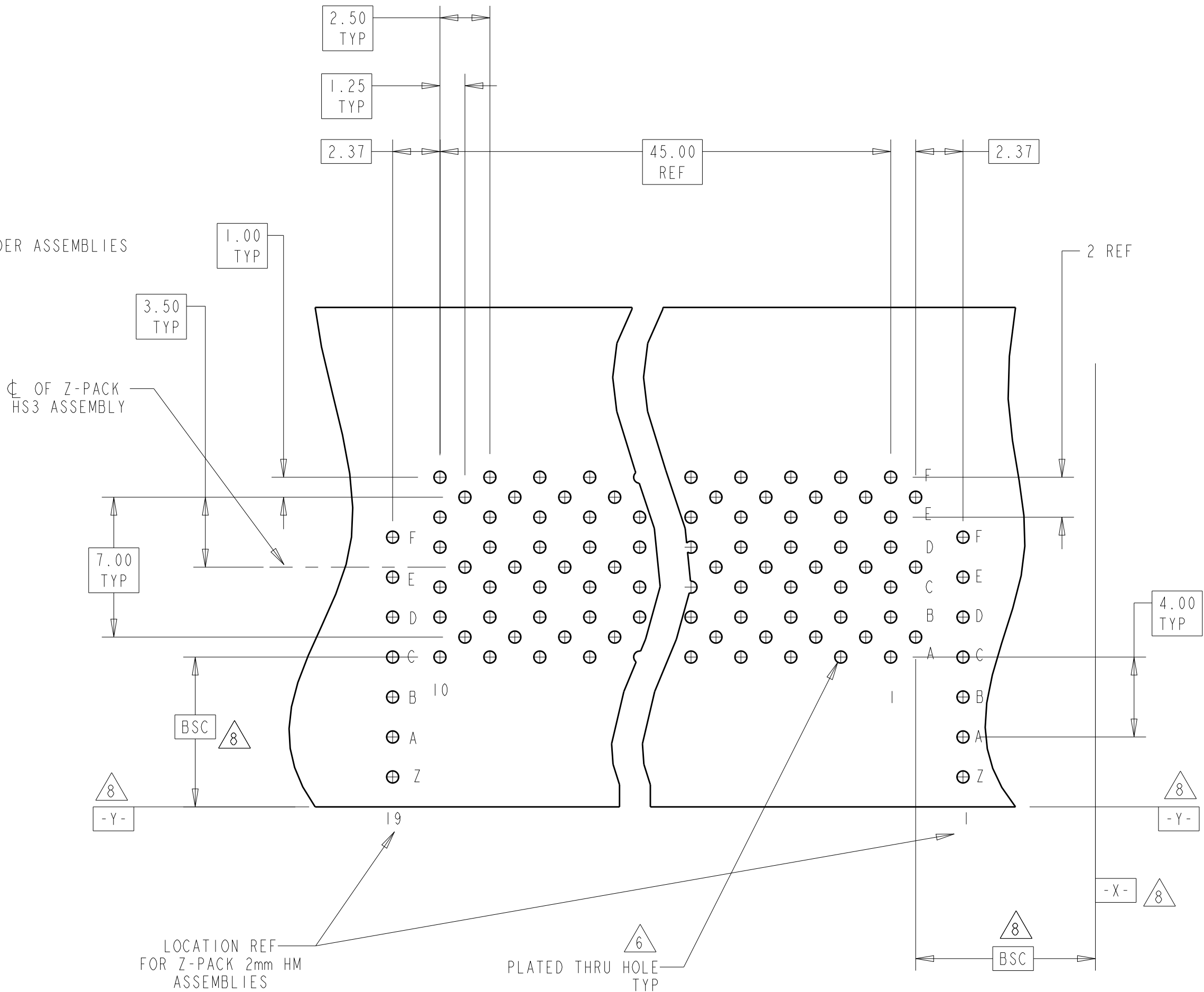
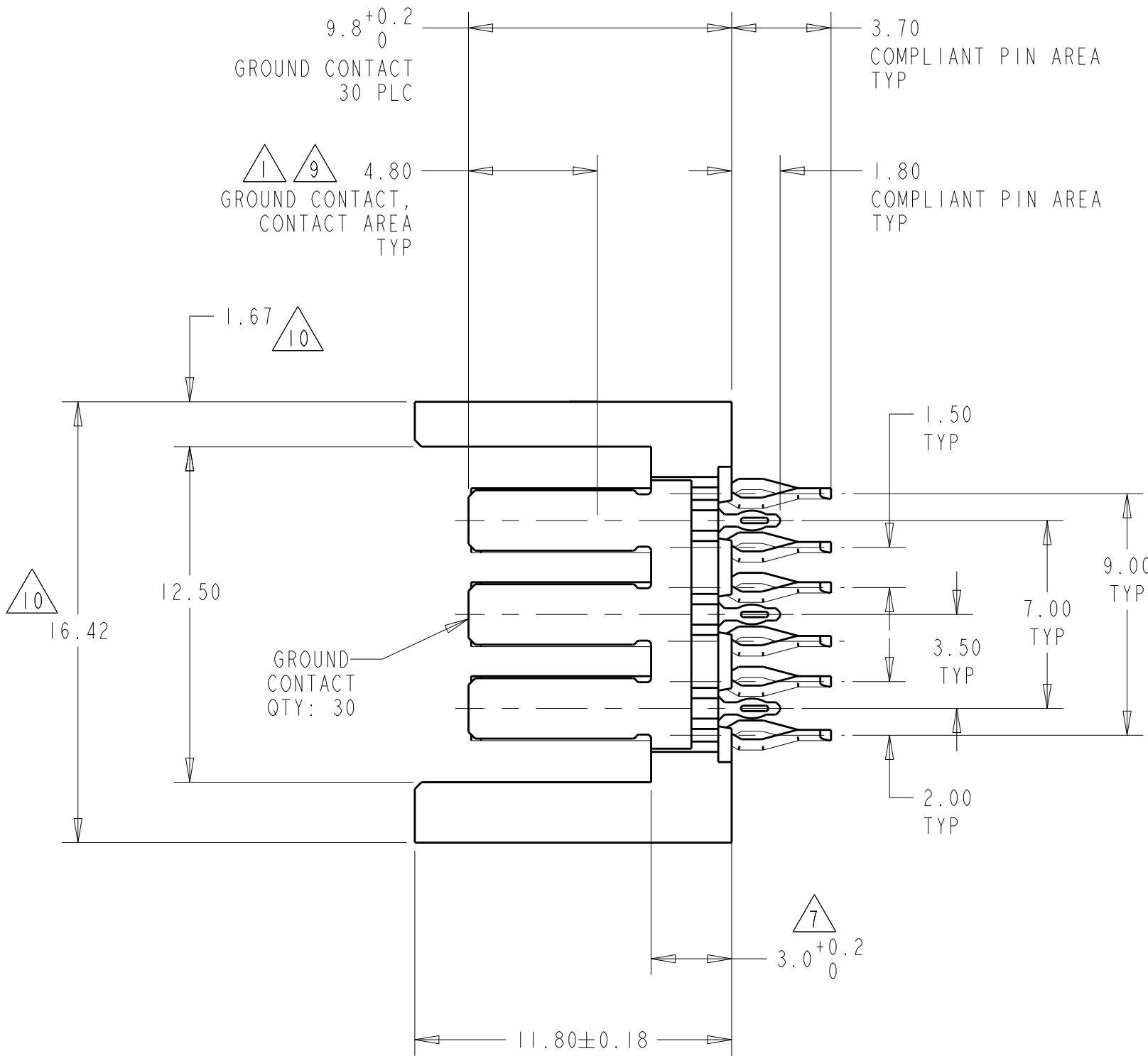
LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
AD	00		B	REVISED PER ECO-12-006972	23AUG2012	KH	JE



SECTION B-B



- 1 FINISH: CONTACT MATING AREA MEETS THE PERFORMANCE REQUIREMENTS OF TE CONNECTIVITY PRODUCT SPECIFICATION 108-1957; BASED ON TELCORDIA GR-1217-CORE, APPLICATIONS IN UNCONTROLLED ENVIRONMENTS. COMPLIANT PIN AREA: 0.5µm MIN MATTE TIN OVER BASE PLATING.
- 2 PHOSPHOR BRONZE
- 3 GLASS FILLED POLYESTER
- 4 0.76µm MIN GOLD OVER 1.27µm MIN NICKEL ON CONTACT AREA
0.76µm MIN TIN OVER 1.27µm MIN NICKEL ON COMPLIANT PIN AREA
- 5 CONNECTOR MARKED WITH PART NUMBER AND DATE CODE
- 6 REFERENCE APPLICATION SPEC 114-13020 FOR RECOMMENDED PLATED THRU HOLE DIAMETER AND PLATING THICKNESS.
- 7 APPLICATION SEATING HEIGHT TO PRINTED CIRCUIT BOARD
- 8 DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
- 9 CONTACT AREA LUBRICATED WITH BELLCORE APPROVED LUBRICANT
TECHNICAL REFERENCE: GR-1217-CORE, ISSUE 1, NOVEMBER 1995
- 10 THIS Z-PACK HS3 HEADER IS SPECIFICALLY DESIGNED TO FIT TWO (2) HEADER ASSEMBLIES IN THE P4 POSITION ON A 20mm SLOT PITCH AGAINST Z-PACK 2mm HM 5 ROW HEADER ASSEMBLIES FOR CompactPCI



THIS DRAWING IS A CONTROLLED DOCUMENT.			DWN B. CARBO	08DEC04	 TE Connectivity		
			CHK R. PATTERSON	08DEC04			
			APVD R. PATTERSON	08DEC04			
DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:			NAME HEADER ASSEMBLY, 60 POSITION, BACKPLANE CONNECTOR, 6 ROW, Z-PACK HS3 FOR CompactPCI		
mm		0 PLC ±					
		1 PLC ±0.13					
		2 PLC ±0.05					
		4 PLC ±			SIZE A1		
		ANGLES					
MATERIAL		FINISH GROUND CONTACT:			CAGE CODE DRAWING NO		
HOUSING:							
CONTACTS:		SIGNAL CONTACT:			©=5120826		
					CUSTOMER DRAWING		
					SCALE 5:1		